Beyond DOS: The UEFI Shell – a Modern Pre-boot Application Environment

Mike Rothman, Sr. Staff BIOS Software Engineer, Intel
Jaben Carsey , Staff BIOS Engineer, Intel
Nathan C Skalsky, Staff Firmware Engineer, IBM
Jeff Bobzin, UEFI Architect, Insyde

EFIS005

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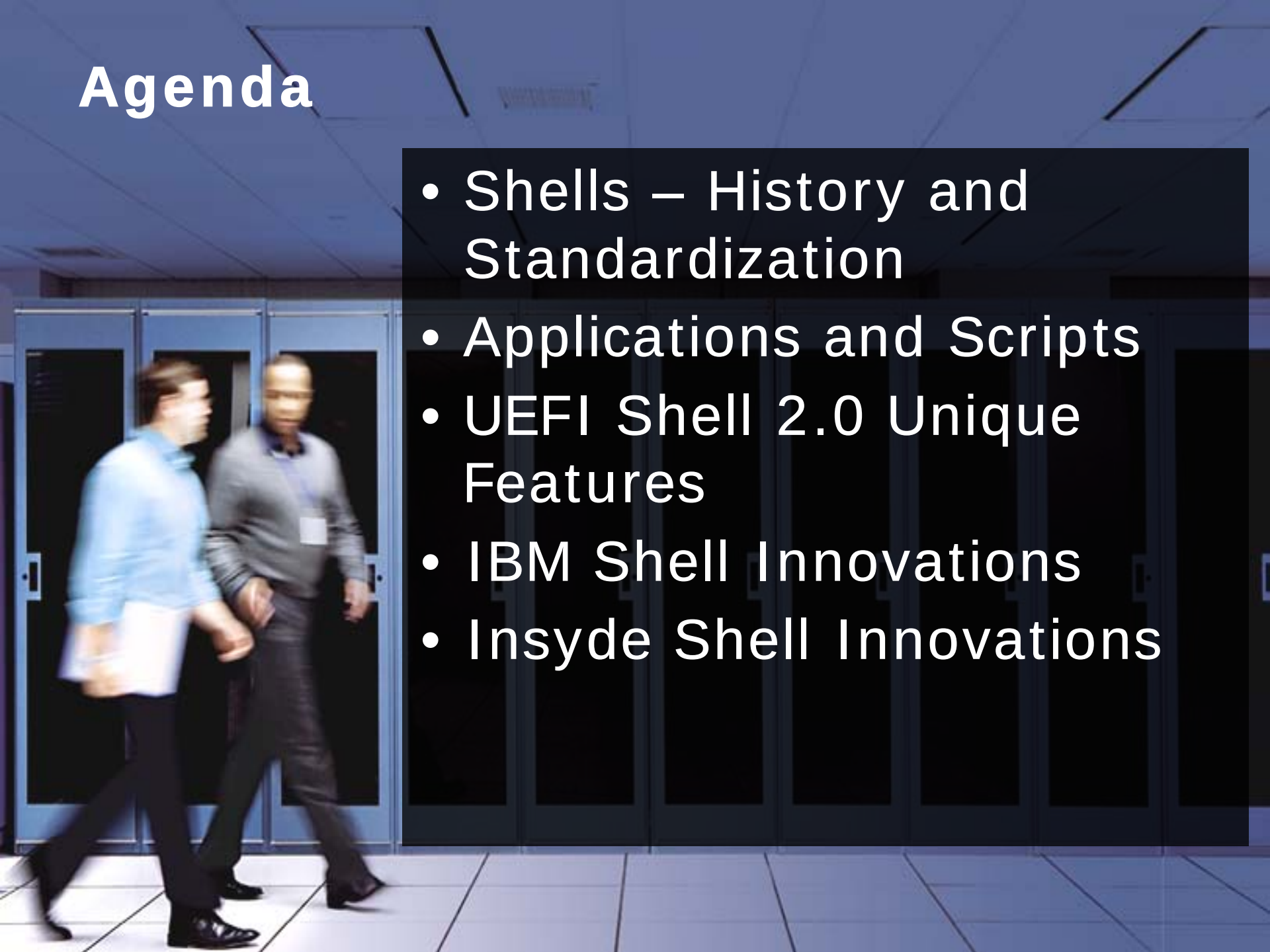
Agenda



- Shells – History and Standardization
- Applications and Scripts
- UEFI Shell 2.0 Unique Features
- IBM Shell Innovations
- Insyde Shell Innovations

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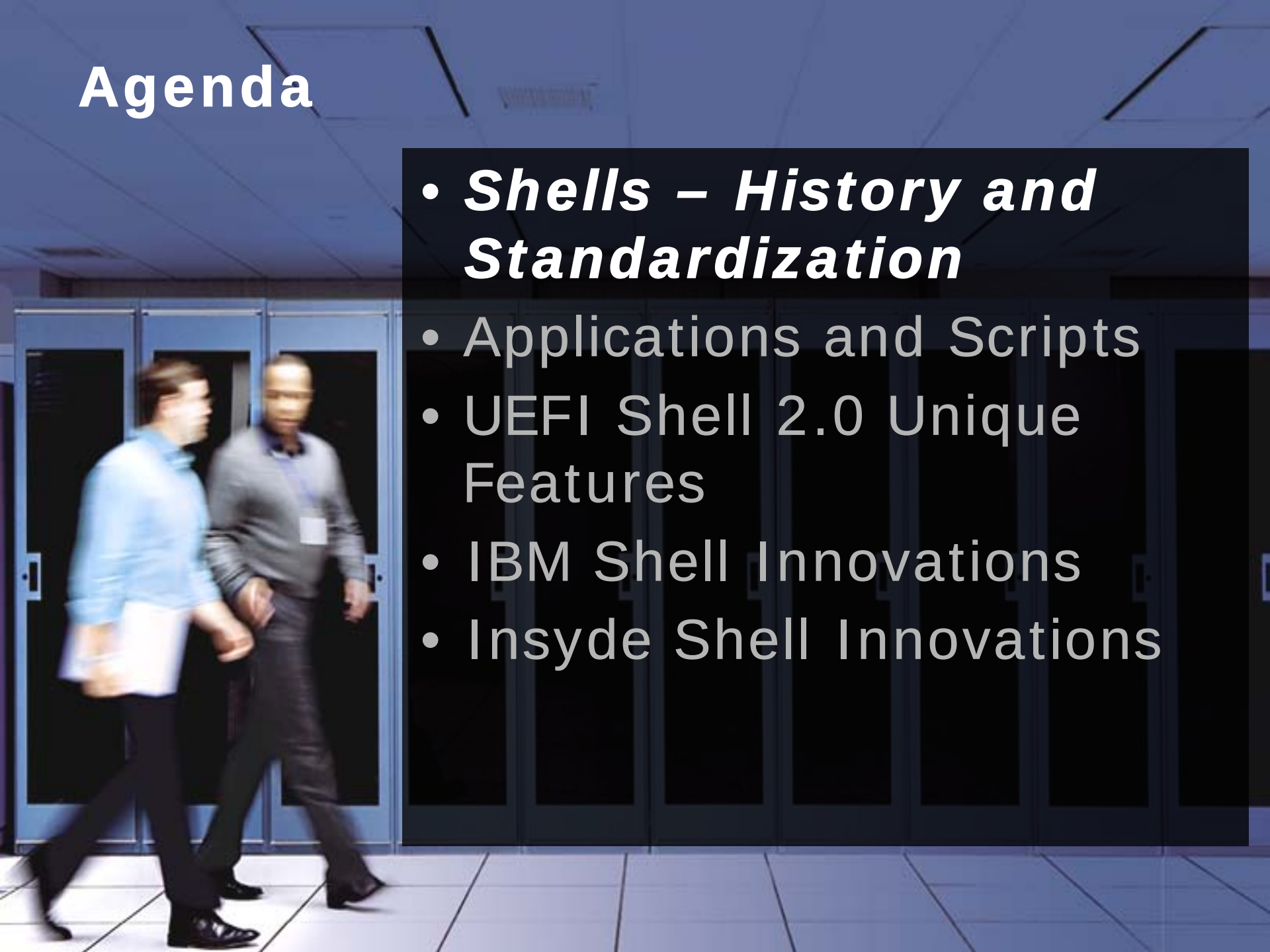

- ***Shells – History and Standardization***
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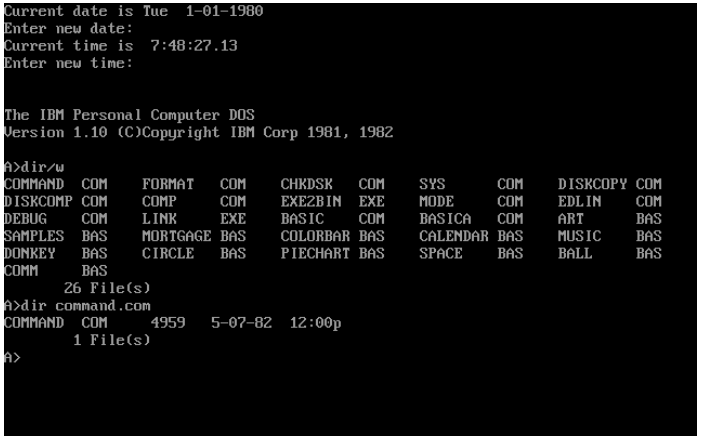
Shells – History and Standardization

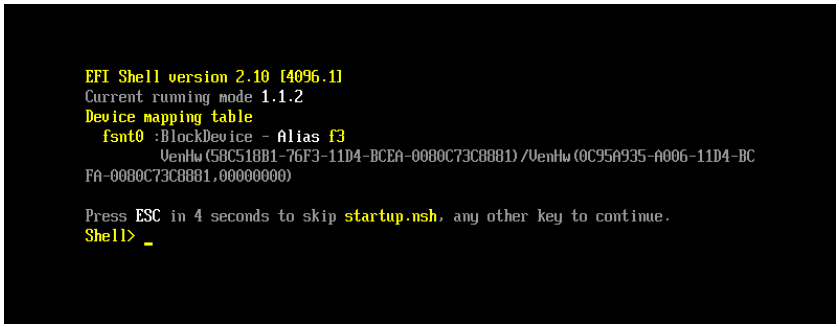
- History of Command-lines
  - Early 1970's – Unix arrives
  - Early 1980's – DOS arrives
  - Today – Most O/Ses expose a command-line
- Command-line uses
  - Scripting
  - Program Launching
  - Abstraction to underlying system
  - Bring-up Target



PC DOS 1.1

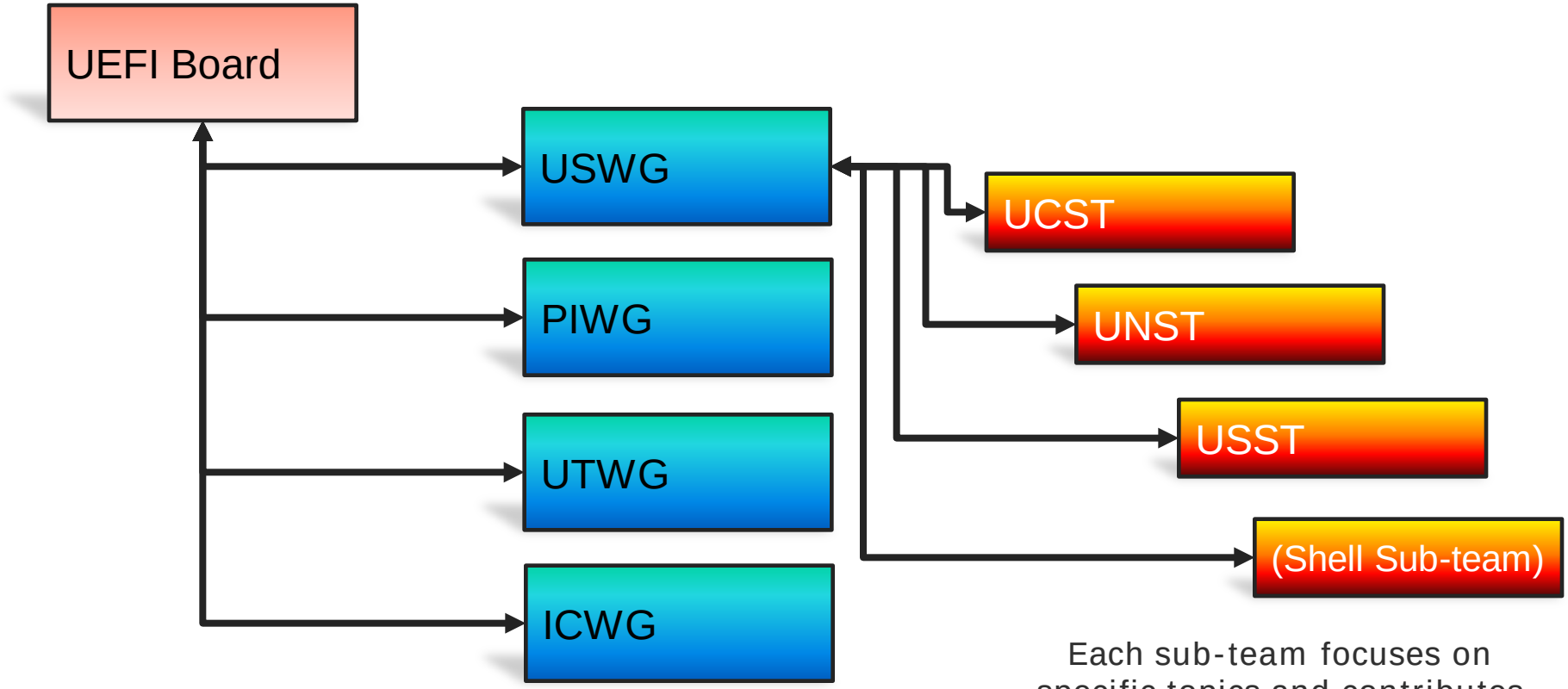
Modern version

of DOS



UEFI Shell

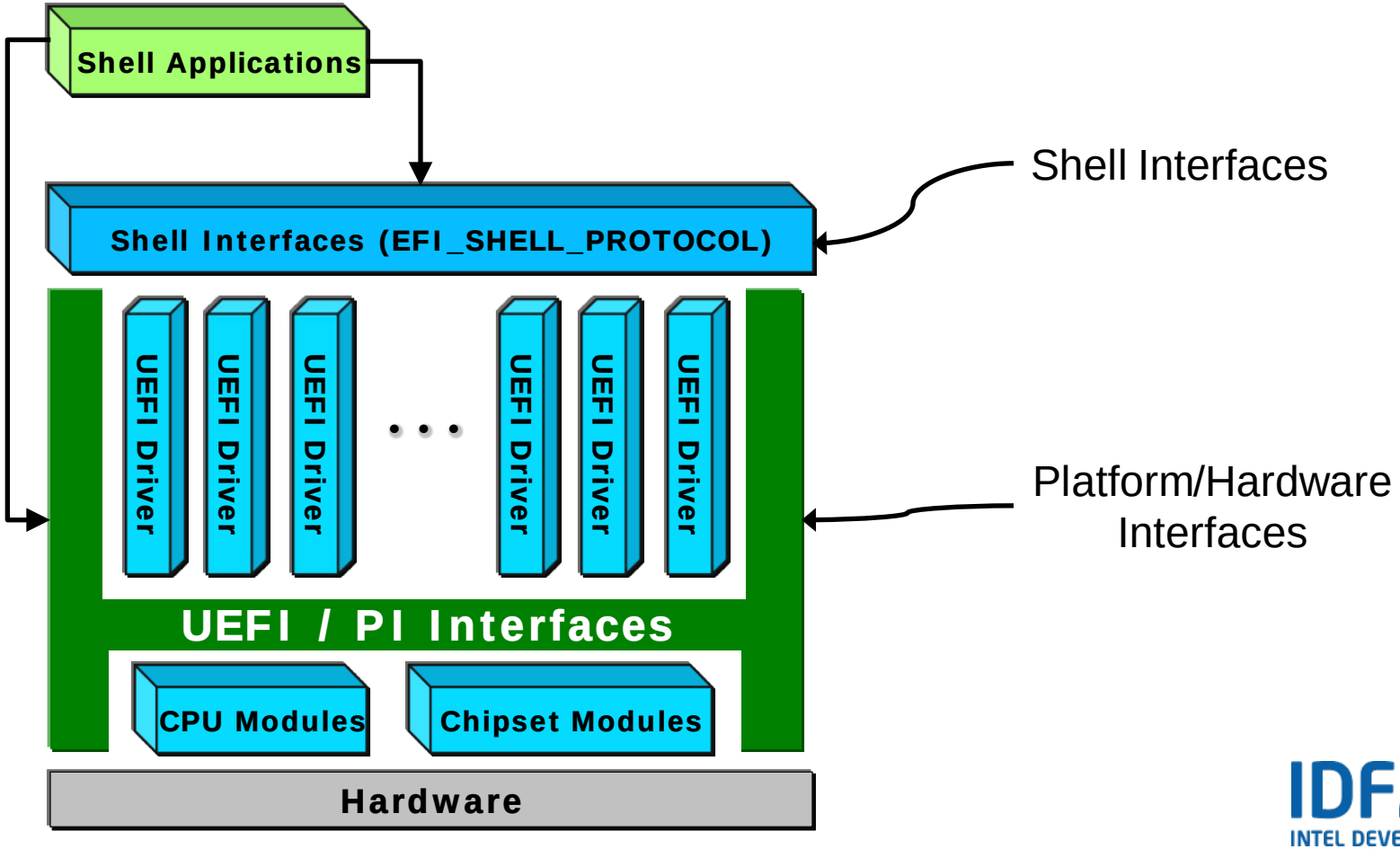
Shells – History and Standardization



The presence of standards enables interoperability

Shells – History and Standardization

- Reusable code regardless of UEFI implementation.
  - Due to scripting and programmable methods being standardized.



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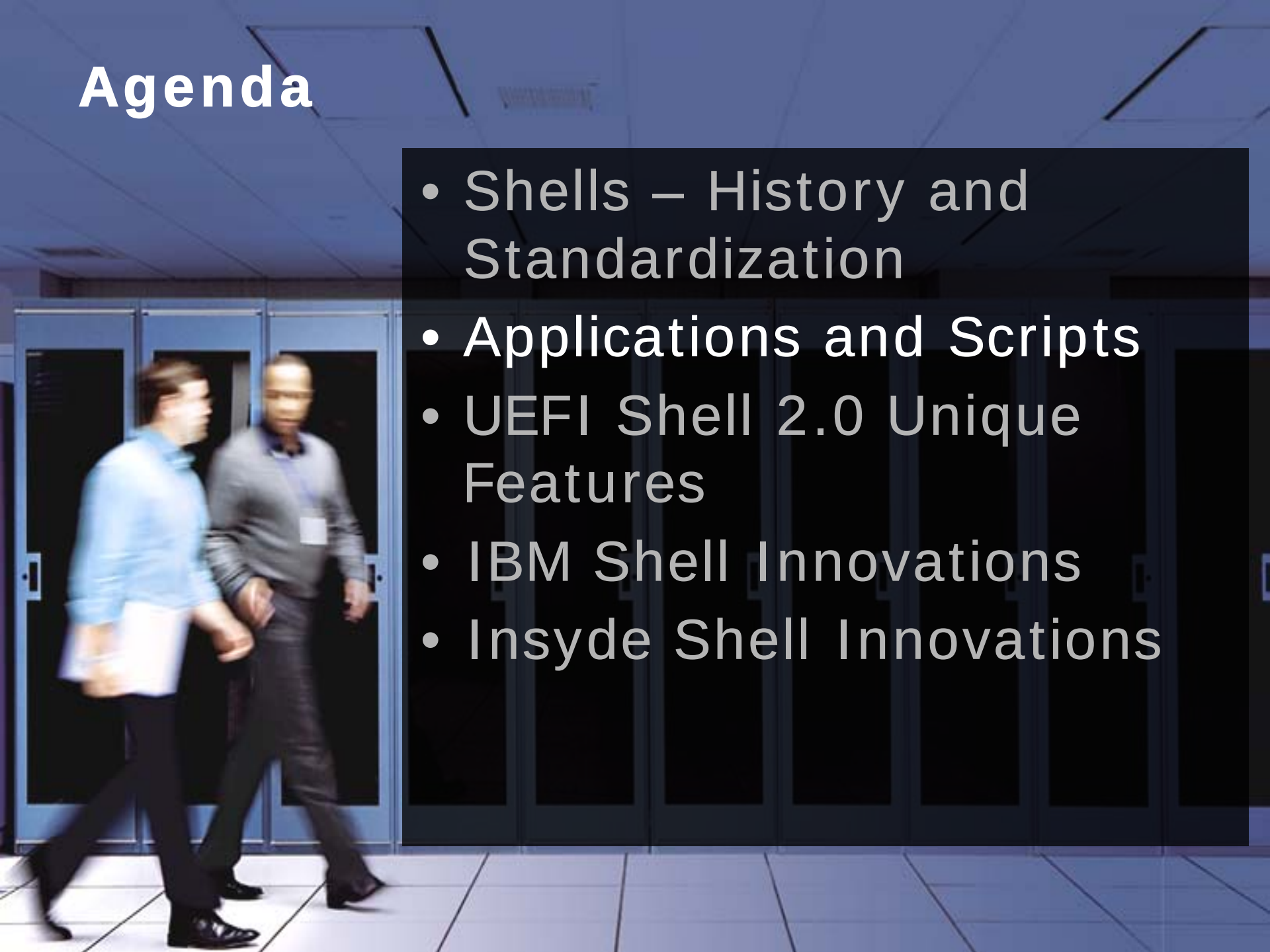

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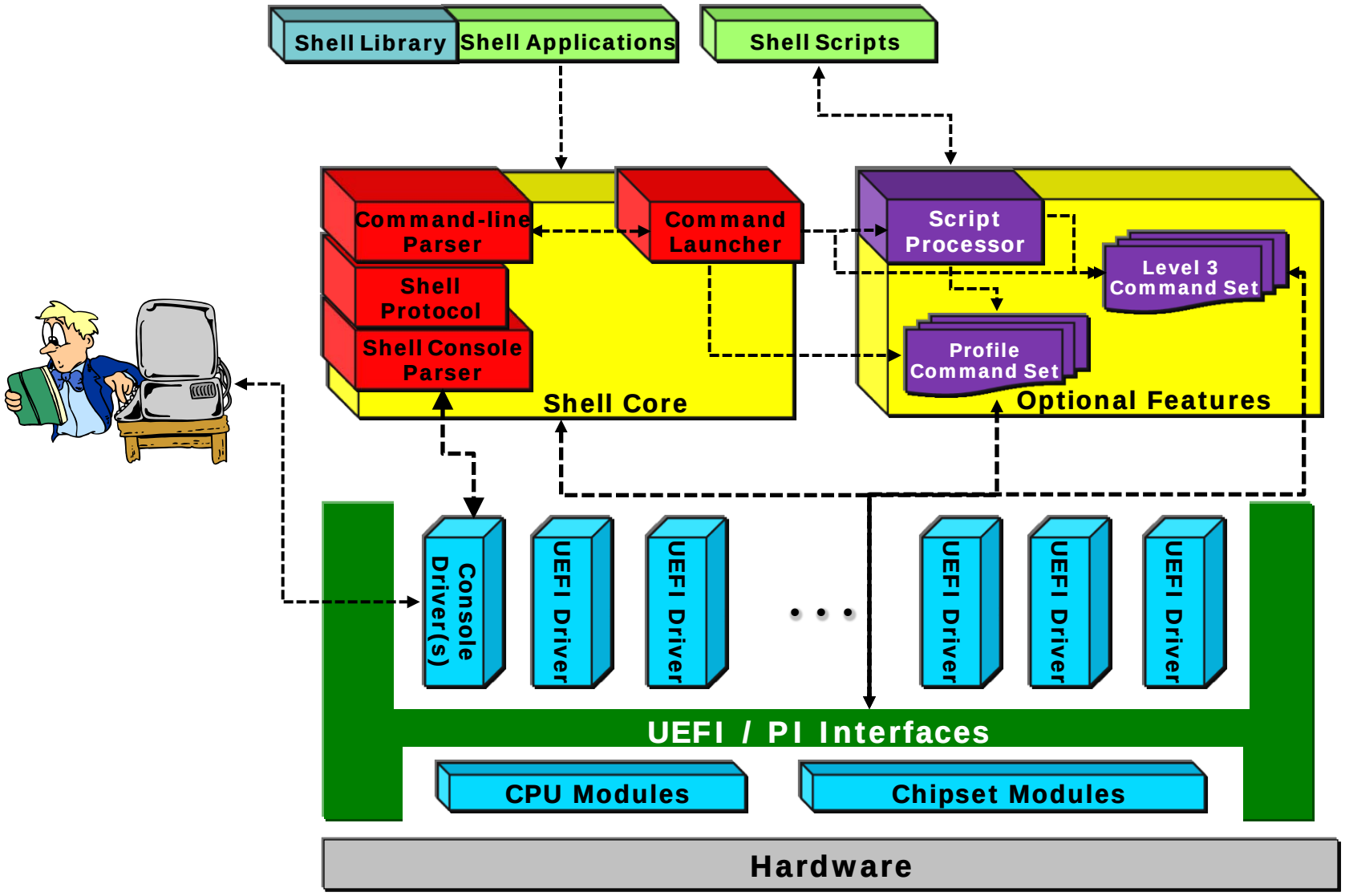
A UEFI Shell 2.0 Architecture



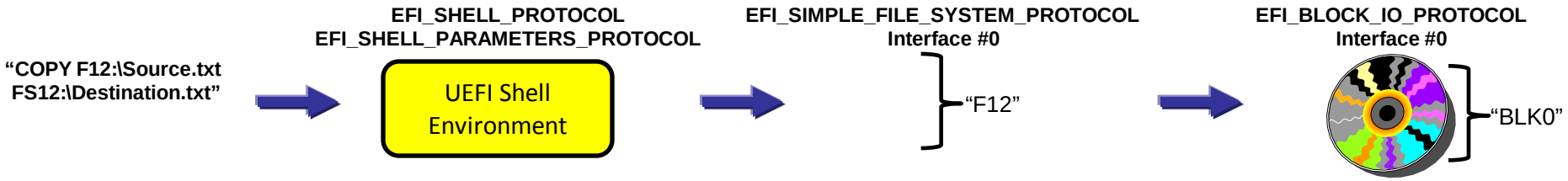
Shell Applications

- UEFI Shell 2.0 applications are compiled C code binaries that:
  - Use a Shell protocol
    - **EfiShellProtocol** – provides APIs for file IO and Shell Environment IO
    - **EfiShellParametersProtocol** – provides Std I/O and Argc/Argv
  - Optionally use UEFI protocols
  - Are launched from command line, script, or in startup parameters to the shell itself

Shell Applications replace EFI Shell Extensions

Shell Scripts

- Shell Scripts (.nsh files) provide automated execution of sequences of shell commands, shell or UEFI applications, and other shell scripts
- Support complex logic via For, If, and Goto
- Route human readable commands to correct hardware

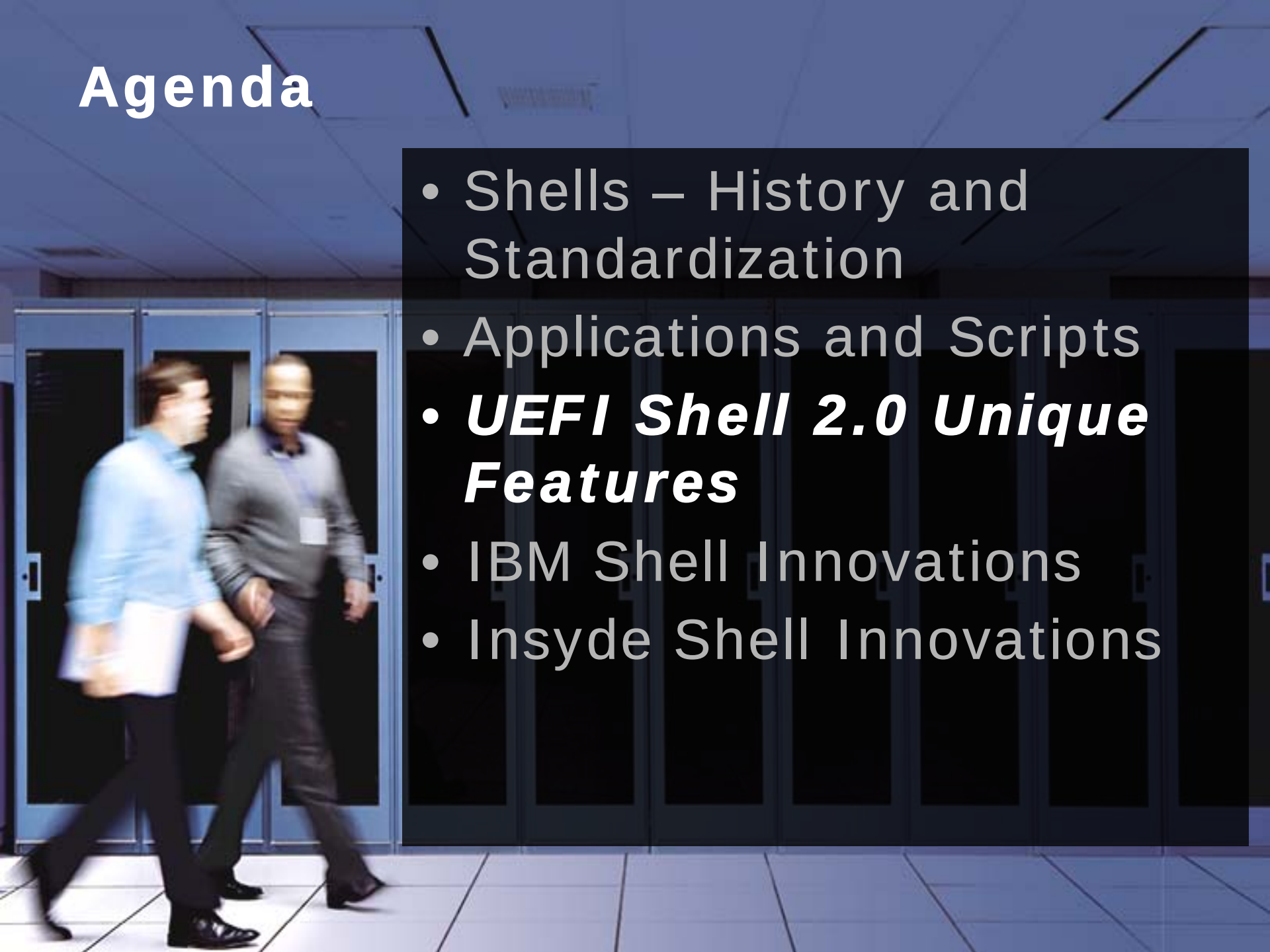


What's Changed?

- EFI Shell scripts remain compatible
- UEFI 2.0 Scripts have additional capabilities
  - Query for command availability
  - Consistent Command feature sets

- Old Shell Protocols deprecated
- UEFI Shell Protocols added
  - EFI Shell extensions require porting
  - UEFI applications will work
- New UDK Shell Lib supports both Protocols

Agenda



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Key UEFI Shell 2.0 Features

New features provided by UEFI Shell are:

- Configure command sets available to end users configured at built time
- Provide backwards compatibility with existing shell scripts
- Manage firmware image size

```
[PcdsFixedAtBuild]

gEfiShellPkgTokenSpaceGuid.PcdShellSupportLevel  | 3
## bit 0 = Drivers1, bit 1 = Debug1, bit 2 = Install1, bit 3 = Network1
gEfiShellPkgTokenSpaceGuid.PcdShellProfileMask    | 0xF
```

UEFI Shell Command Sets

- Shell Levels manage main features
  - Level 0 – Launching a single application
  - Level 1 – Adds scripting
  - Level 2 – Adds file manipulation
  - Level 3 – Adds UI and information retrieval
- Shell Profiles manage additional commands
  - Install – Adds OS loader configuration
  - Debug – Adds debug
  - Driver – Adds driver manipulation
  - Network – Adds network configuration & test

Unique ability to balance required features and commands against desired binary size

Shell.EFI Image Size Management

- Maximum Image Size
  - Level 3 shell with all 4 defined profiles
  - Supports all standard commands and a UI for interaction with an user
- Minimum Image Size
  - Level 0 shell with no profiles
  - Supports launching a single application
- Additional extra profiles possible

64 size combinations available!

Agenda

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IBM Experience

"Smarter Firmware for a Smarter Planet"

Nathan C. Skalsky
Advisory Firmware Engineer, IBM
September 13th, 2010

Agenda

- IBM's UEFI Shell 2.0 roadmap
- Key Features of UEFI Shell
- Running the UEFI Shell on IBM System x
- Example Uses of UEFI Shell
  - Bring Up
  - Development
  - System Manufacturing
  - Deployment/Provisioning
  - Maintenance
  - Debug
- Conclusion

IBM

UEFI Shell 2.0 Roadmap

- **Compatibility:** All UEFI-compliant System x Servers and Blades.
- **Integrated Shell:** a built-in level 3 UEFI Shell 2.0 is planned to be available via x86 IBM eX5 firmware updates within the next year.
  - Available as a Boot Item
  - Launch-able via UEFI Shell
- **Tools/CLI Strategy:** Current direction is to continue to use OS-based pre-boot deployments environments for flashing/in-band configuration updates. Shell is considered a supplementary command-line environment.

Key Features UEFI Shell 2.0

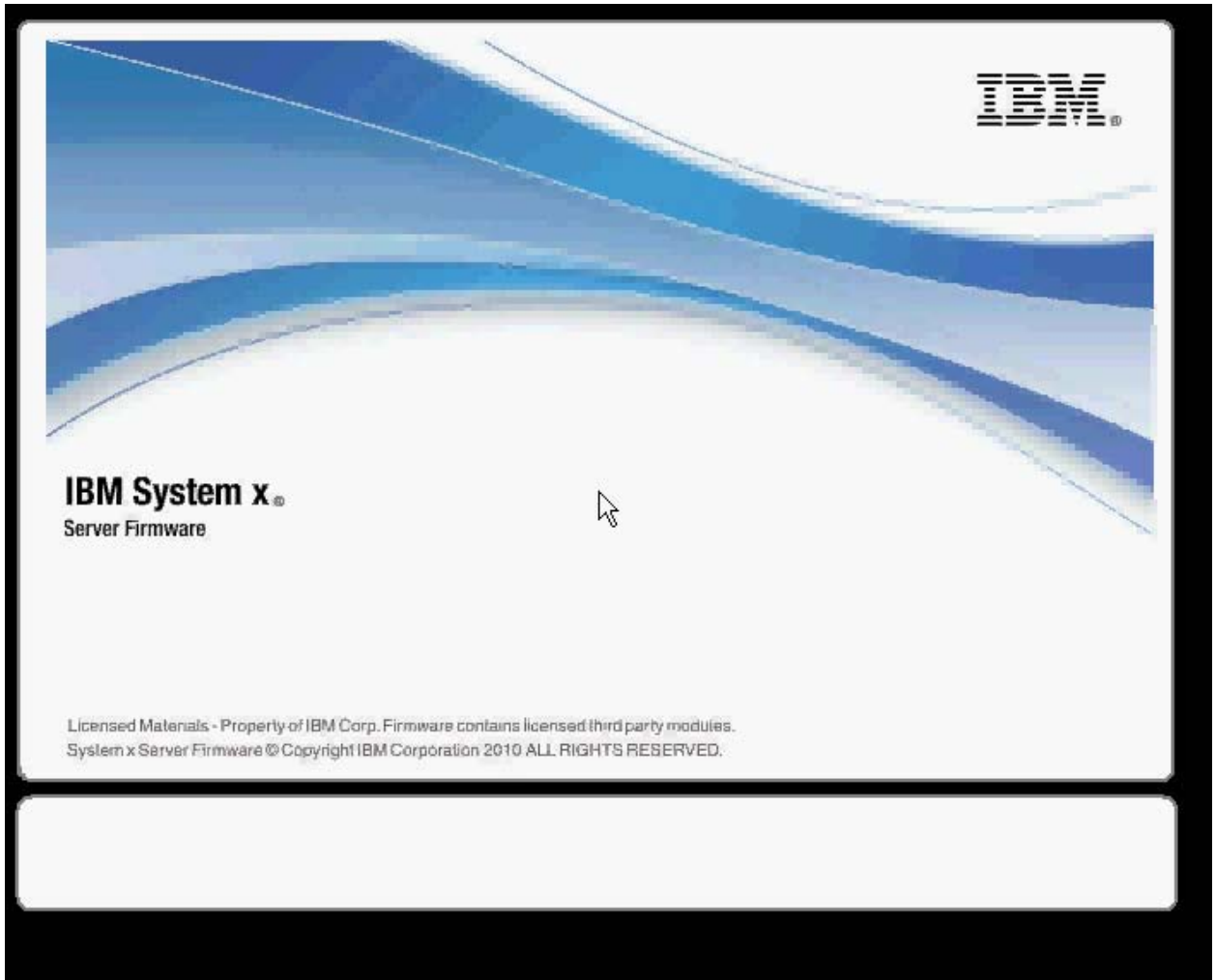
- "Common-Denominator" Preboot CLI
  - No dependencies on OS load / deployment
  - Direct-hardware environment
- Embeddable and flexible foot-print
- Scripting
  - Automating Configuration/deployment tasks
  - Automating Testing (reset tests, verify OS interfaces, run UEFI standards compliance tool (SCT)
- Shell Libraries enable ease of development and portability of applications
- Execute UEFI binaries
- Load/Unload Pre-Boot UEFI/DXE Drivers

Key Application Areas of UEFI Shell 2.0

- Early Hardware “Bring-up” Milestone
- Development and Testing
- Manufacturing
- Deployment/Provisioning
- Maintenance
- Debug / Product Support Investigations

Launching and Using UEFI Shell 2.0

- **One-Time**
  - F1 Setup → Boot Manager → Boot From File
- **As a Boot Option**
  - F1 Setup → Boot Manager → Add Boot Option



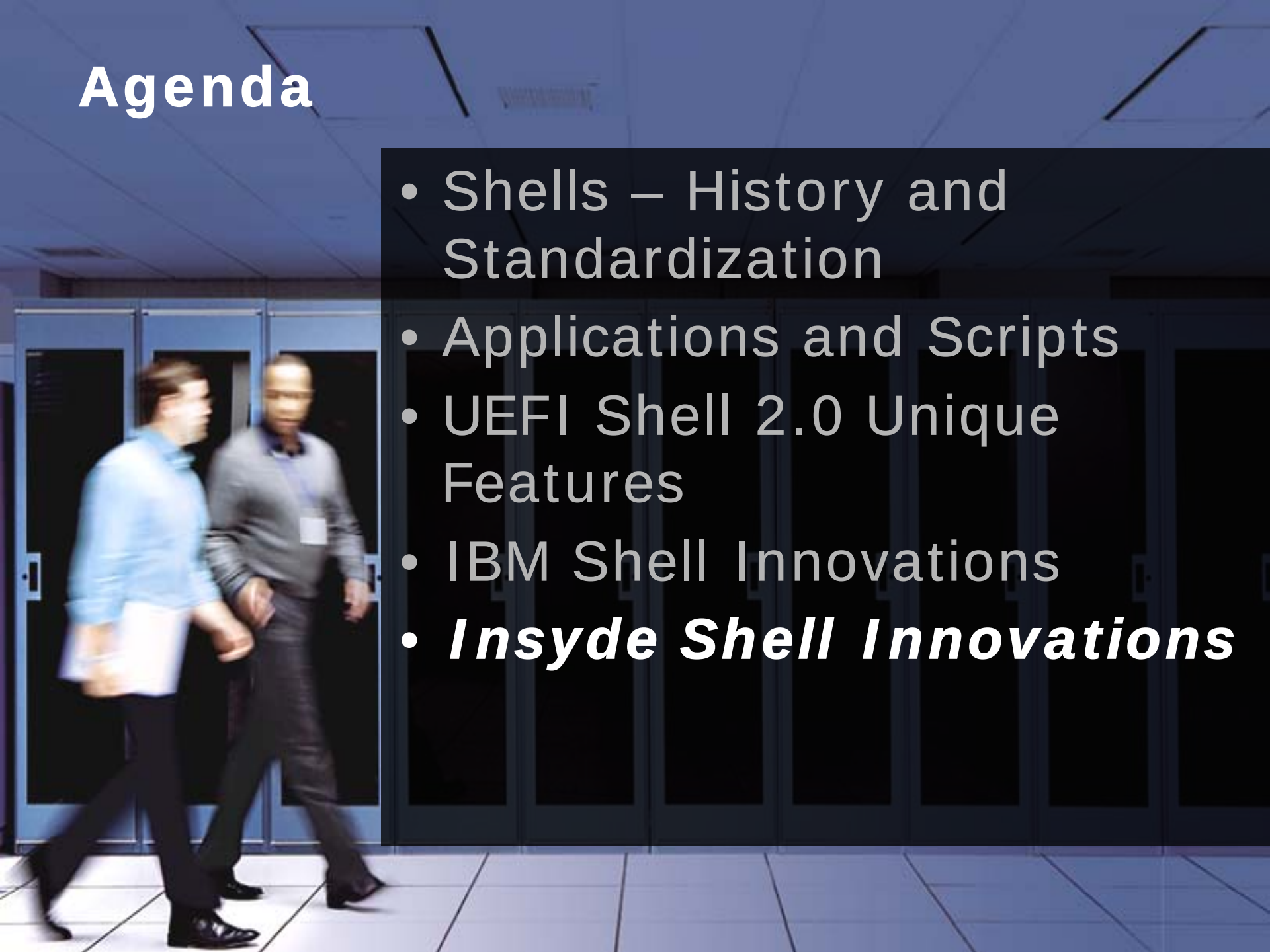
Using UEFI Shell during Development

- Scripting: Startup.nsh (think “Autoexec.bat”)
- Commands: DumpVariable/PCI/IbmHiiParse

Conclusion

- UEFI Shell 2.0 is a powerful “common denominator” environment and set of IO/console libraries
- IBM and IBM vendors heavily leverage the shell for bring-up, development, and debug activities
- Future is bright for automated and interactive configuration, deployment and update use-cases

Agenda



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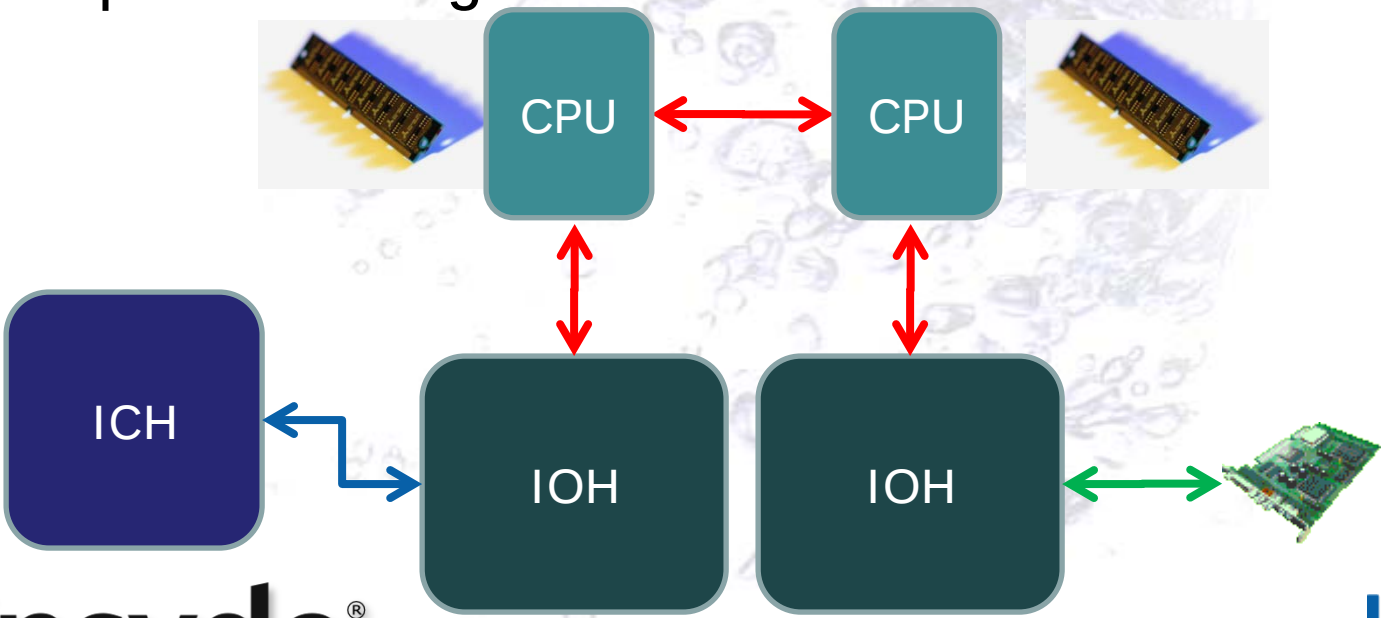
Using the Pre-Boot Application Environment

- Network Browsing

- Complex Testing



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Riding on top of a Network Capable Shell…

- Extends pre-boot space onto Internet
- Network Browsing Examples:
  - IT department support page
    - Help pages
    - Http download client
    - Access to OS recovery images
  - Remote assist system
    - System drivers download from OEM service site
    - Remote system diagnostic
    - Hardware support page

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Demo of Network Browsing

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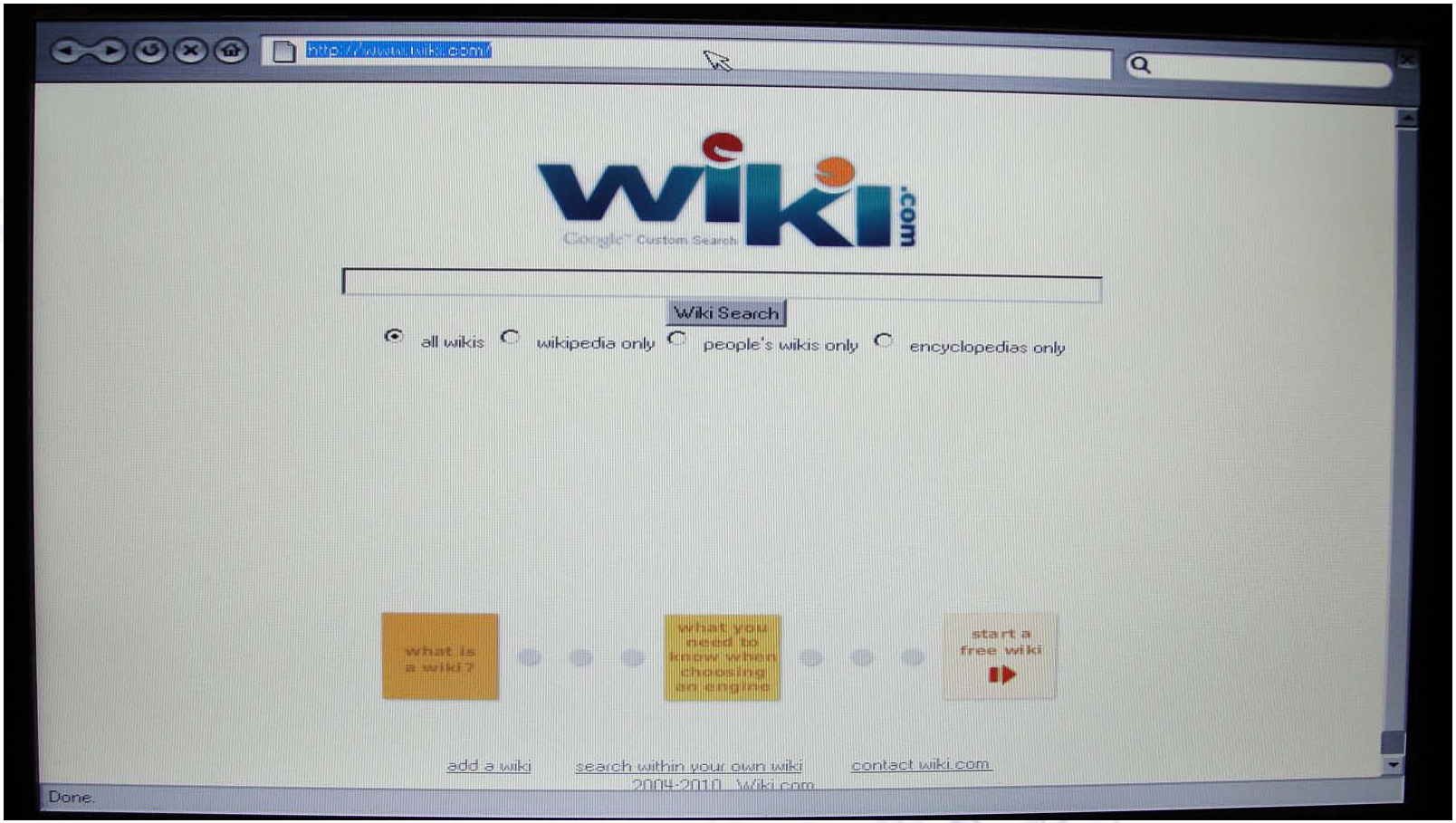
Network Browsing in UEFI…coming soon!



Networking sets applications free in the pre-boot space

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Complex Testing in a shell application

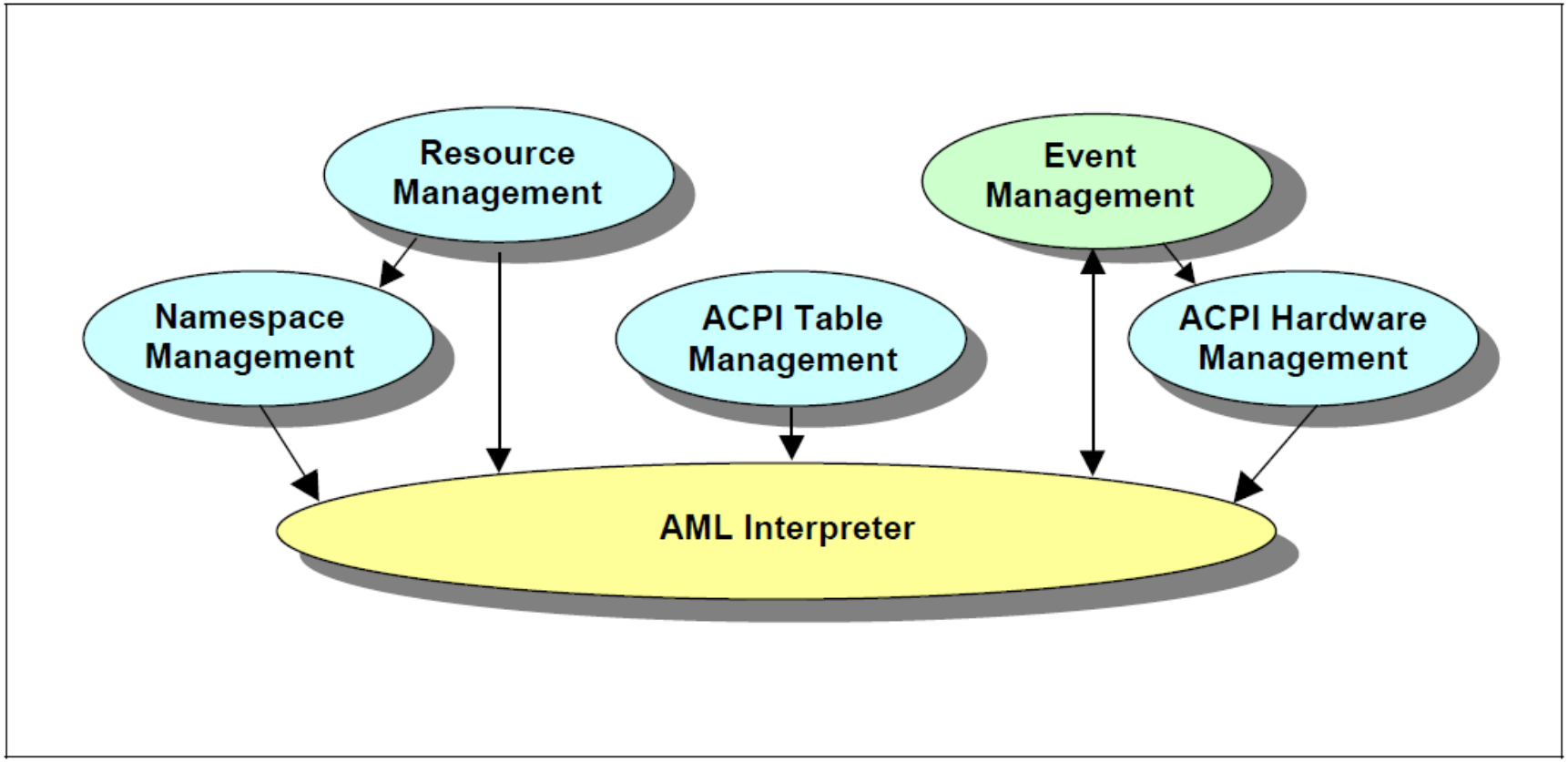
- Test hardware features not supported in OS
- Accelerate hardware feature development
  - Simpler debug environment than OS
  - More control for probing error conditions
- Enable efficient testing of features
  - Rapid test cycles booting just to UEFI Shell
  - Specific error cases can be validated

RAS Feature development and testing…

- OSes have limited support
  - Processor offline
  - Memory offline
- Need “live” ACPI environment
  - Methods and events supported
  - ACPI Component Architecture (ACPICA) is candidate
    - Designed for OS integration
    - Open source code base
    - Used in Linux and other Oses
    - Excellent APIs for OS abstraction
- Why port ACPICA subsystem to UEFI shell?
  - UEFI is good fit for rapid testing and prototyping
  - UEFI protocols suitable to provide needed APIs

ACPICA Internals

- Internal Modules of the ACPICA Core Subsystem



Porting ACPICA

- Use standard C libs
- Use UEFI API to provide hardware access
- Use UEFI periodic timer events to monitor

```
ACPI_STATUS AcpiOsReadPciConfiguration (
ACPI_PCI_ID  *PciId,       UINT32  Register,
void         *Value,       UINT32  Width){

UINT64                  Pciex_Address=0;

Pciex_Address = CALC_EFI_PCIEX_ADDRESS (PciId->Bus,
                  PciId->Device,PciId->Function, Register);
switch (Width)    {
case 8:
    Status = gRootBridgeIo->Pci.Read (gRootBridgeIo,
        EfiPciWidthUint8, Pciex_Address, 1, Value);
…
```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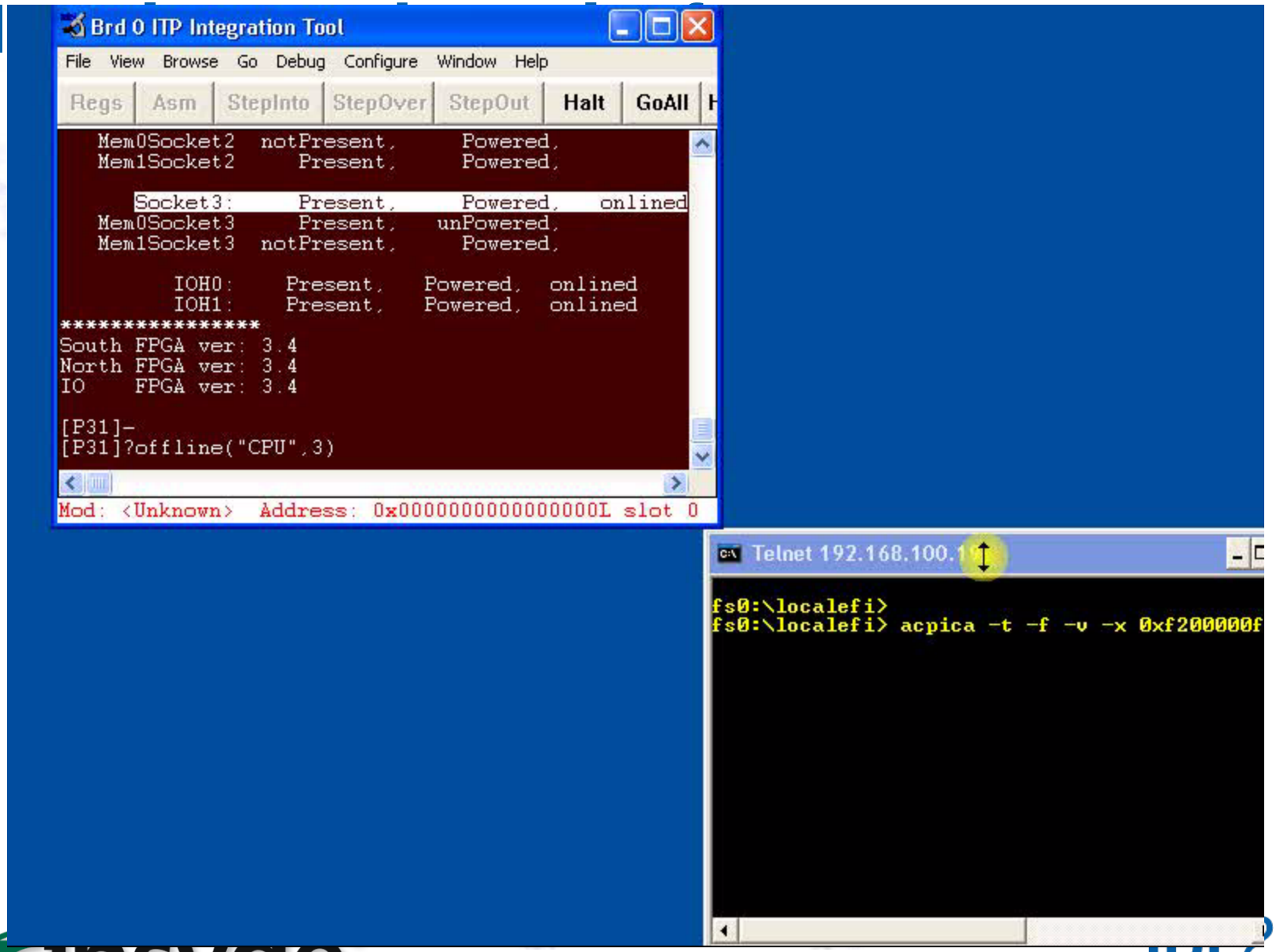
Demo ACPICA running on



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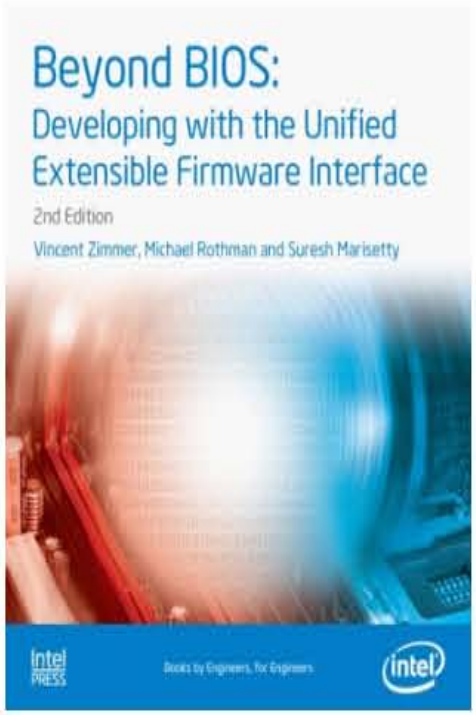
Summary

- Shell 2.0 implementation fully compliant to UEFI Shell Specification now available on tianocore.org
- Configure your shell to meet feature set and image size sweet spot
- Network profile sets applications free in the pre-boot space
- UEFI Application environment is great test harness

Additional sources of information on this topic:

- Other Sessions – Next Slide
- Demos in the showcase – EFI Booth, #160
- More web based info:
  - ***UDK 2010 - http://www.tianocore.Sourceforge.net***
  - ***UEFI Specifications - http://www.uefi.org***
- Book on topic:
  - Beyond BIOS 2nd edition - Intel Press
- Get the UEFI Shell 2.0 specification – www.uefi.org.
- Get the UDK ShellPkg with all the source code from www.tianocore.org

Beyond BIOS 2nd Edition Promotion



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Vouchers available in session room and UEFI Tech showcase booth #160

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UEFI PLUGFEST in Taiwan Oct 12-15,

Visit www.uefi.org/events for Event Info and Registration

IDF 2010 UEFI Fall Sessions
Sept. 13, 2010 Moscone Room 2006

EFI#	Company	Description	Time
✓ S001	Intel, IBM, HP	Introducing the New Intel® UEFI Development Kit: Industry Foundation for Platform Innovation	11:00 AM
✓ S002	Intel, LSI, Dell, Phoenix	UEFI Advancements for Independent Hardware Vendors	1:05 PM
✓ S003	Intel, WindRiver	Boot Loader Solutions for Intel® Atom™ Processor Based Embedded Devices	2:10 PM
✓ S004	Intel, Dell, AMI	Zero-Touch Platform Manageability with UEFI	3:15 PM
✓ S005	Intel, IBM, Insyde	Beyond DOS: The UEFI Shell – a Modern Pre-boot Application Environment	4:20 PM
Q001	All	UEFI Q & A session with all Speakers	5:25 PM

✓ DONE

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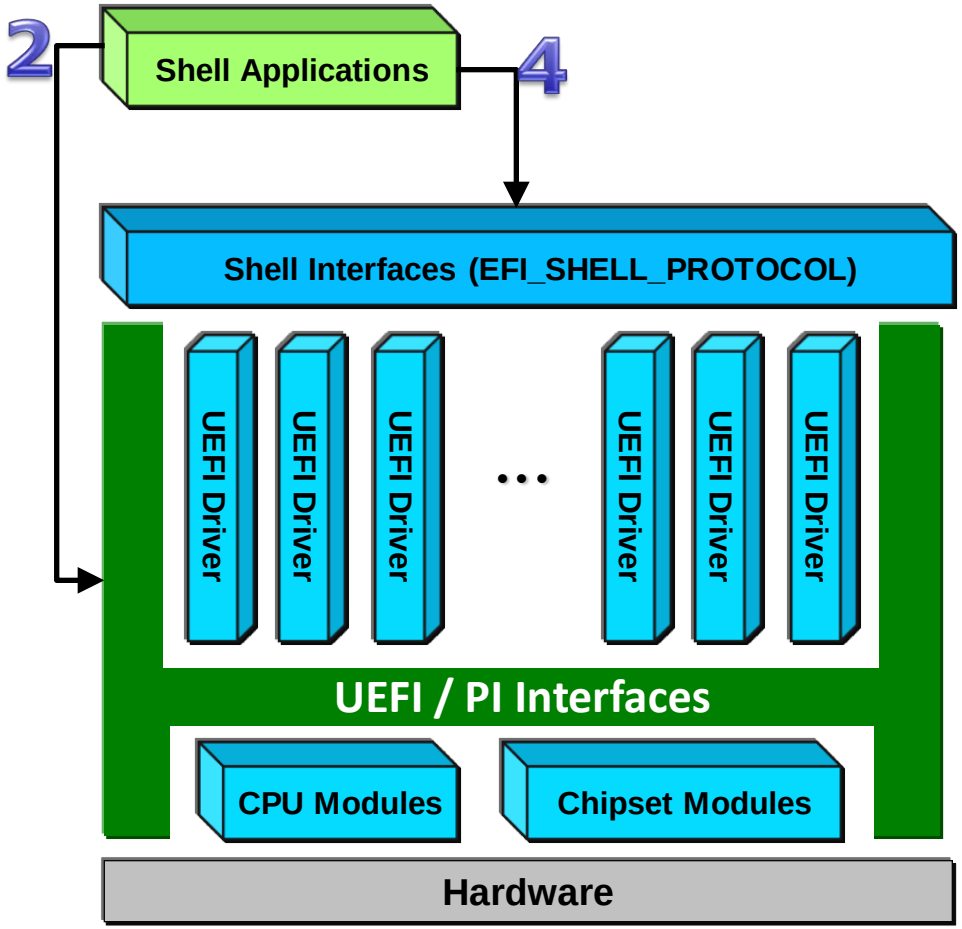
Backup Slides




```
EFI_STATUS
EFIAPI
InitializeApplication (
1  IN  EFI_HANDLE                ImageHandle,
   IN  EFI_SYSTEM_HANDLE         *SystemTable
   )
{
3  EFI_SHELL_APP_INIT (ImageHandle, SystemTable);

  //Program Logic follows
  …
}
```

1) This item illustrates what the standard entry point for any UEFI compatible binary application or driver looks like. This is the fundamental starting point for all UEFI compatible programs which exposes the underlying UEFI firmware services.
2) During the initialization of a UEFI program, the standard entry point would be used to access the standard runtime and boot services that the UEFI compatible firmware provides.
3) In most shell-aware applications, there would be either a library or macro which would be used to provide access to the underlying shell protocol interfaces. This library/macro isn't required by the UEFI shell specification, but would commonly be found in many of the available shell-aware programs.
4) In shell-aware applications, the availability of the functions defined in the EFI_SHELL_PROTOCOL can be leveraged.